

ABSTRACT OF THE DISCLOSURE

A method of manufacturing a semiconductor mounting board includes providing a base member and linear conductive members formed of metallic wires. The conductive members are constructed so that they extend linearly between a semiconductor element-mounting face and a circuit board-mounting face of a base member, and are integrally molded within the base member. For this purpose, a resin material for forming the base member is injected into a mold wherein the conductive members are linearly arranged beforehand.